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**10G EPON ONU BOSA(10G1270nmTX 10G1577nmRX)****Features:**

- ◆ Coaxial Package
- ◆ InGaAsP/InP MQW-DFB Laser Diode
- ◆ Low threshold, high slope efficiency and high output power
- ◆ Operating Case Temperature: 0°C to +70°C
- ◆ High channel isolation
- ◆ Low return loss
- ◆ Optional with Isolator

**Applications:**

- ◆ EPON ONU side
- ◆ Long distance digital transmission system
- ◆ Cable television system
- ◆ WDM systems

**Absolute Maximum Ratings:**

Parameter	Symbol	Min.	Max.	Unit
Storage Temperature	Tstg	-40	85	°C
Operating Case Temperature	Topr	0	70	°C
Reverse Voltage(LD)	V <sub>RL</sub>	---	2	V
Reverse Voltage(PD)	V <sub>RD</sub>	---	20	V
Photodiode Forward Current(PD)	I <sub>FD</sub>	---	2	mA
LD Direct Forward Current	I <sub>FL</sub>	---	120	mA
Lead Soldering (Temperature)/(Time)	---	---	260/10	°C/Sec

**Electrical and Optical Characteristics – Transmitter:**

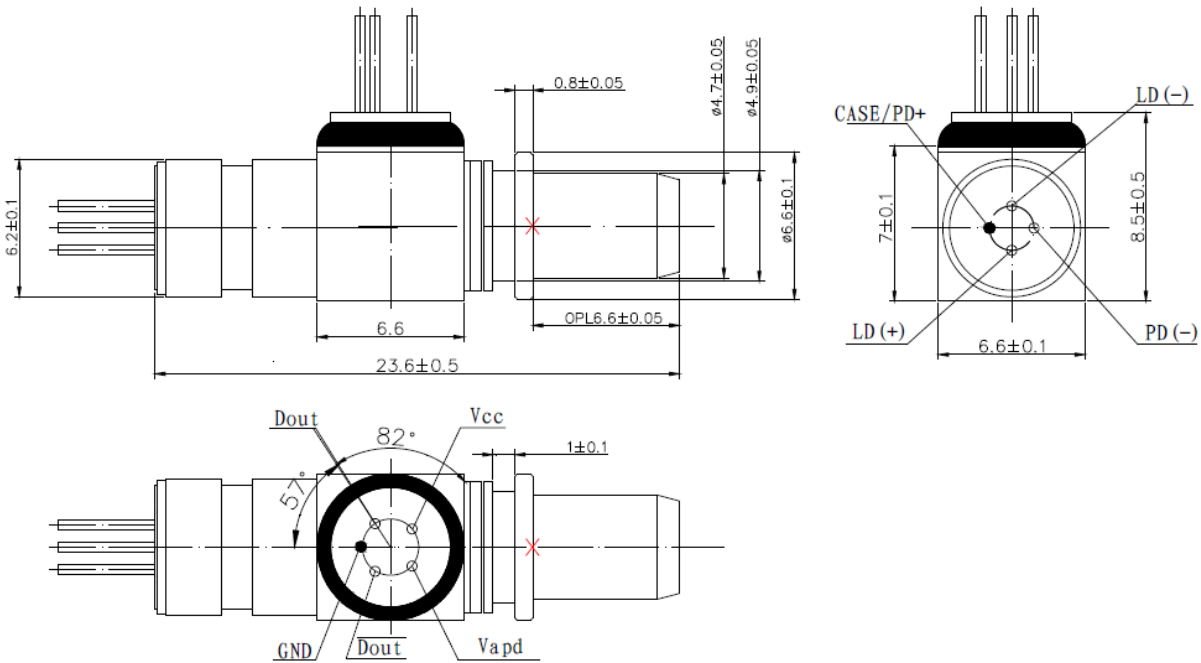
Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Output Optical Power	Pf	2.5	---	---	mW	CW, Iop=Ith+20mA
Threshold Current	Ith	---	8	15	mA	at Tc=25°C
Peak Wavelength	$\lambda_p$	1260	1270	1280	nm	Tc=25°C
Side Mode Suppression Ratio	SMSR	35	40	---	dB	CW, Tc=0~85°C
Operating Voltage	Vop		1.2	1.7	V	CW, Iop=Ith+20mA,
PD Monitor Current	Im	0.05	---	1.0	mA	CW, Iop=Ith+20mA,
Monitor Dark Current	Id	---	---	0.1	$\mu$ A	V <sub>RD</sub> =5V
Optical Isolation	Iso	-30	---	---	dB	---
Tracking Error	TE	-1.5	---	1.5	dB	Iop=Ith+20mA, 0°C/+25°C,+25°C/+70°C

**Electrical / Optical Specifications – Receiver:**

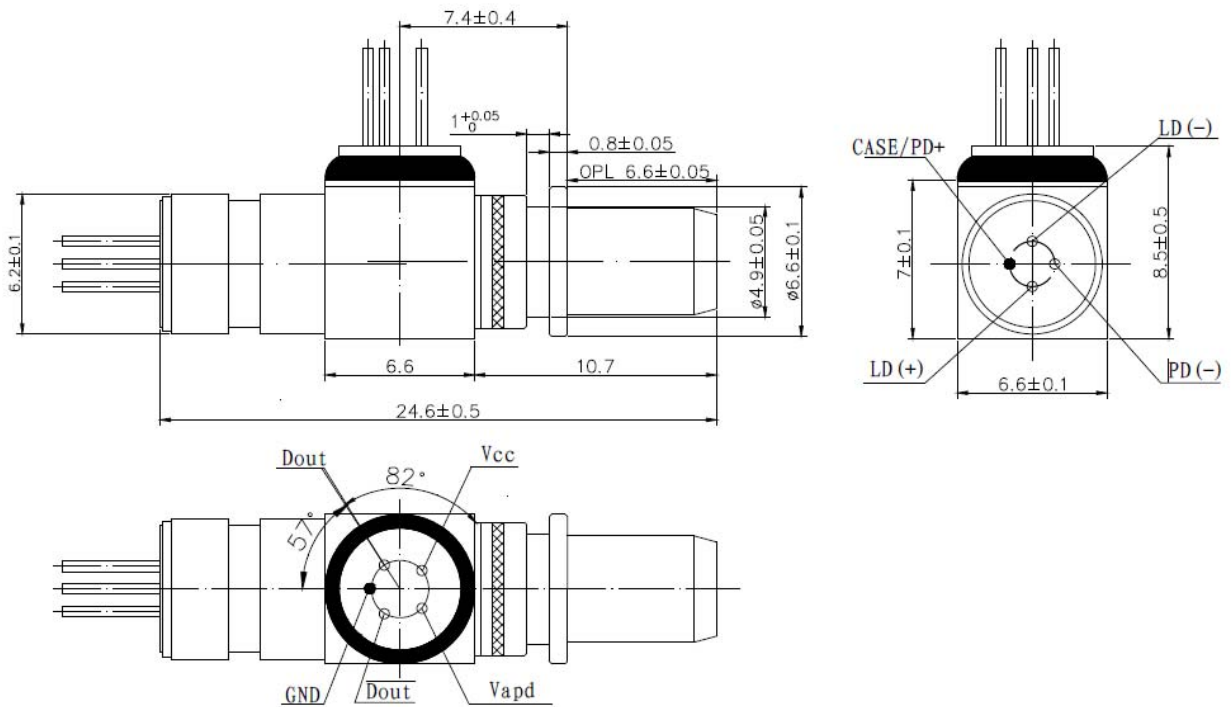
Description	Symbol	Min.	Typ.	Max.	Unit	Note
Operating Wavelength	$\lambda$	1575	1577	1580	nm	
Supply Voltage	Vcc	3.0	3.3	3.6	V	
Supply Current	Icc	40	55	70	mA	
Break-down Voltage	Vbr	25	34	40	V	Id=10 $\mu$ A
APD Responsivity	R	0.65	---	---	A/W	M=1, V <sub>R</sub> =10V
Optical Isolation From External Source	ISO	30	---	---	dB	$\lambda$ = 1310/1490/1550nm
Optical Crosstalk From Internal Laser	Xopt	---	-45	-40	dB	

Package Dimension:

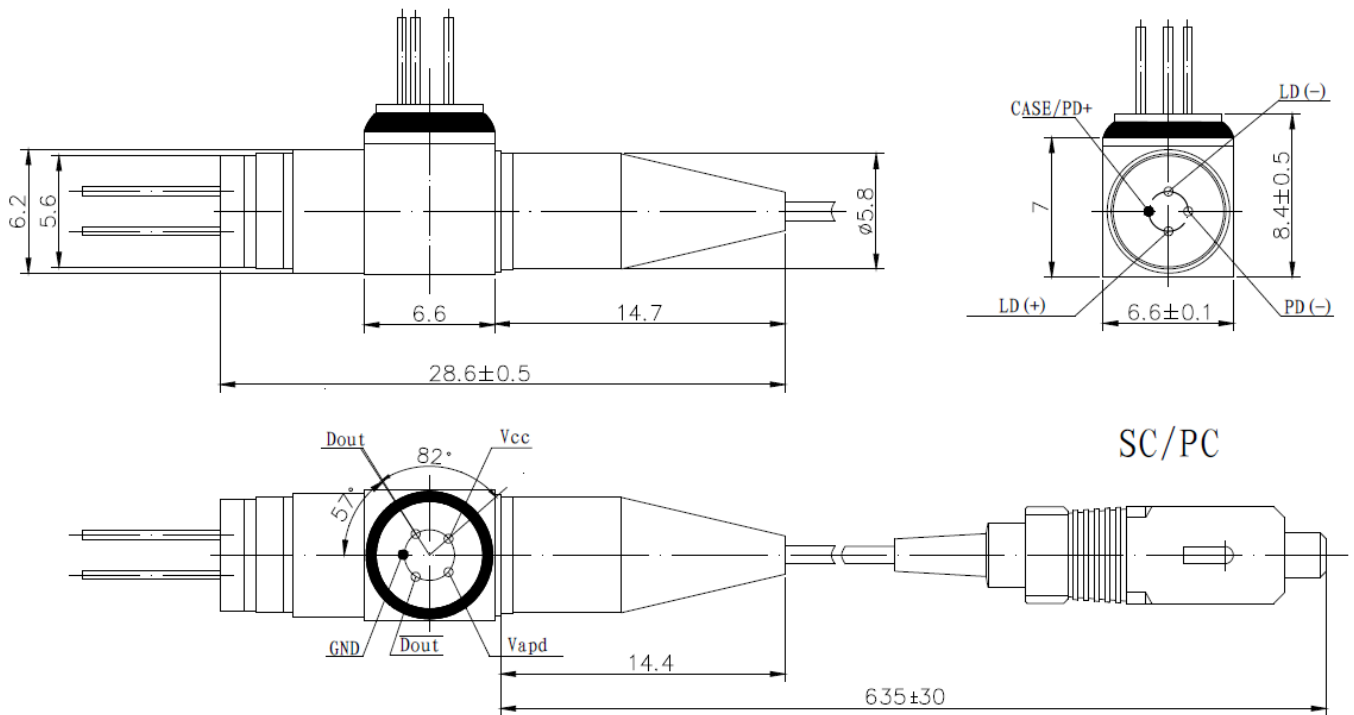
SC/PC receptacle (Non-electrical isolation)



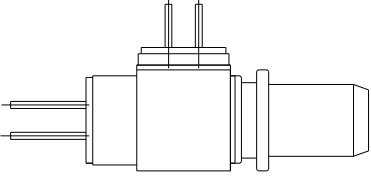
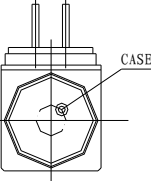
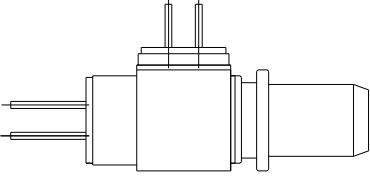
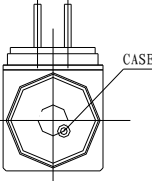
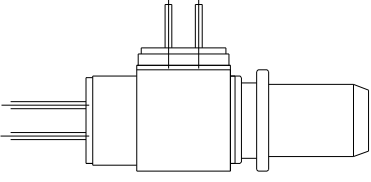
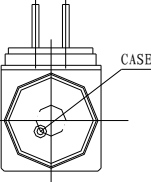
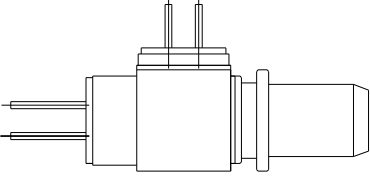
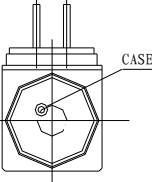
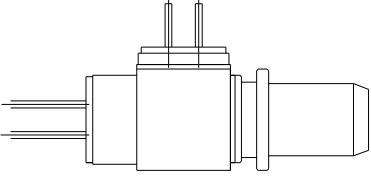
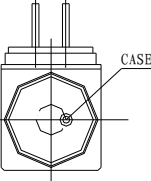
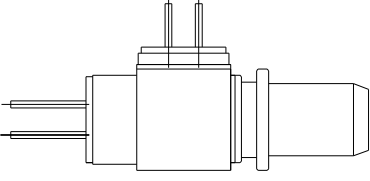
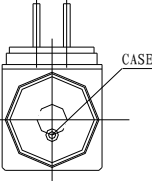
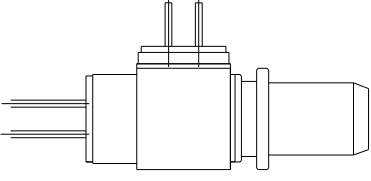
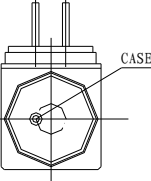
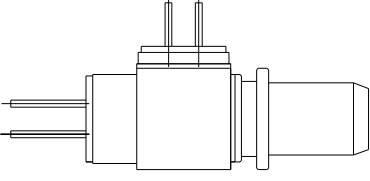
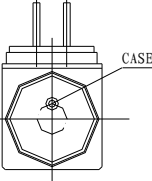
SC/PC receptacle (Electrical isolation)



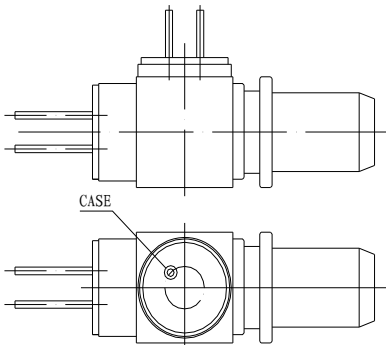
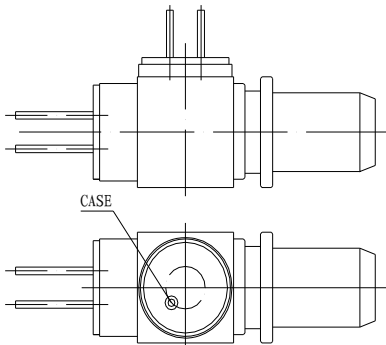
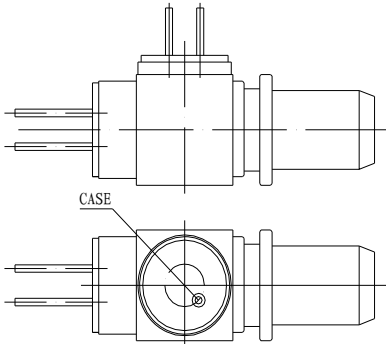
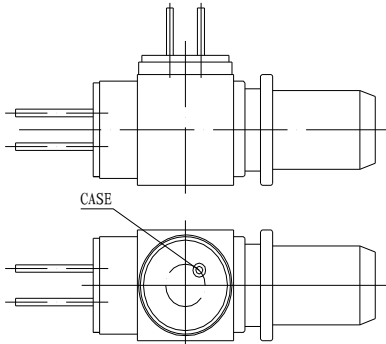
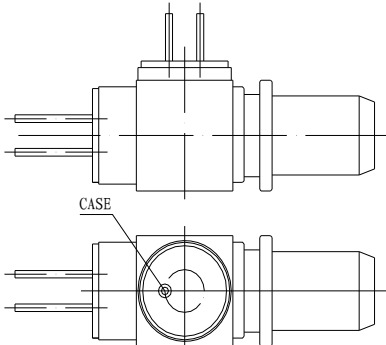
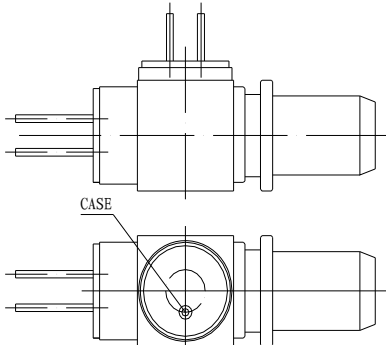
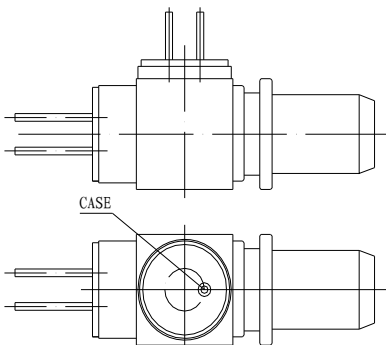
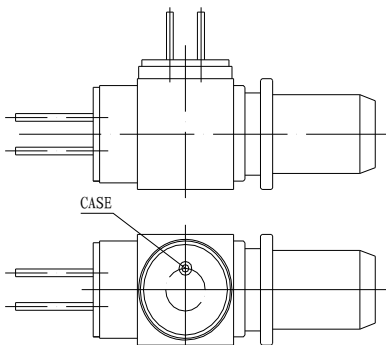
## PBIDI-SC/PC:



**TX Pin Order Code:**

Launch			
			
Case direction	A Type	Case direction	B Type
			
Case direction	C Type	Case direction	D Type
			
Case direction	E Type	Case direction	F Type
			
Case direction	G Type	Case direction	H Type

**RX Pin Order Code:**

Receive			
			
Case direction	A Type	Case direction	B Type
			
Case direction	C Type	Case direction	D Type
			
Case direction	E Type	Case direction	F Type
			
Case direction	G Type	Case direction	H Type

**Nomenclature:**

HEBIDI-              
A B C D E F G H I J K

Code	Parameter	Detailed Description									
A	Laser Type	D=DFB LD									
B	Launch Wavelength	A=1270									
C	Launch Data rate	1=10G									
D	Output Power	20=2.0~2.99mW									
E	Receiver Wavelength	H=1577									
F	Receiver Data rate	T=10G									
G	Connector	SR= SC/PC receptacle					SP= SC/PC Pigtail				
H	Connector Type	1= Non-electrical isolation					2= Electrical isolation				
I	TX Pin Package Direction	A	B	C	D	E	F	G	H		
J	RX Pin Package Direction	A	B	C	D	E	F	G	H		
K	Isolator	G=with I									

**Precaution:**

- (1) The modules should be handled in the same manner as ordinary semiconductor devices to prevent the electro-static damages. For safe keeping and carrying, the modules should be packaged with ESD proof material. To assemble the modules on PCB, the workbench, the soldering iron and the human body should be grounded.
- (2) Please pay special attention to the atmosphere condition because the dew on the module may cause some electrical damages.
- (3) Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed.

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